



Final Product Change Notification

201402010F01

Issue Date: 08-Jul-2014
Effective Date: 06-Oct-2014

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QUALITY

Management Summary

Thin die TDA3663/4N1 in SO4 (only) at APG.

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input checked="" type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Thin die TDA3663/4 in SO4 at APG

Details of this Change

Thin die TDA3663/4N1 in SO4 at NXP assembly plant Guangdong (APG).

Why do we implement this Change

Standardization for the Assembly site back grind process.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

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Production

Planned first shipment 10-Sep-2014

Impact

no impact to the product's functionality anticipated.

No impact for form, fit or function of the product.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201402010A	03-Mar-2014		Thin die TDA3663/4 in SO4 at APG
201402010AU01	28-Mar-2014		Thin die TDA3663/4 in SO4 at APG

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 07-Aug-2014.

Remarks

n.a.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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